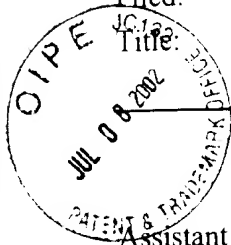


S/N 09/652,430

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Biswajit Sur et al. Examiner: Lisa Lea-Edmonds
Serial No.: 09/652,430 Group Art Unit: 2835
Filed: August 31, 2000 Docket: 884.319US1
Title: ELECTRONIC ASSEMBLY COMPRISING SOLDERABLE THERMAL INTERFACE
AND METHODS OF MANUFACTURE



INFORMATION DISCLOSURE STATEMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Pursuant to 37 C.F.R. §1.97(b), it is believed that no fee or statement is required with the Information Disclosure Statement. However, if an Office Action on the merits has been mailed, the Commissioner is hereby authorized to charge the required fees to Account No. 19-0743 in order to have this Information Disclosure Statement considered.

The Examiner is invited to contact the Applicants' Representatives at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

BISWAJIT SUR ET AL.

By their Representatives,

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Date June 28, 2002

By Ann M. McCrackin
Ann M. McCrackin
Reg. No. 42,858

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner of Patents, Washington, D.C. 20231, on this 28 day of June, 2002.

Jane E. Brockschink

Name

[Signature]
Signature